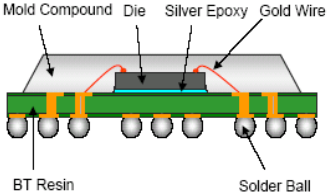


Material Declaration

Compliance Date: Jun./07/2022

RoHS Compliance: Yes

MSL: 3

Pin count /Package		48B BGA (6X8)								
Model (Part) Number		AS6CE4016B-45BIN								
Package Weight (mg)		114.62								
Composed parts	Purpose	Weight (mg)	%	ppm	Material	CAS No.	Weight (mg)	Material wt% of total	Material wt% of Sub part	
Chip	Wafer Circuit	8	6.98	69,796	Silicon (Si)	7440-21-3	8.000	6.980%	100.00%	
Bonding Wire	Conductivity	0.65	0.57	5,671	Gold (Au)	7440-57-5	0.650	0.567%	100.00%	
Die Attach	Die Attach	0.43	0.38	3,752	Synthetic rubber	(Trade secret)	0.009	0.008%	2.00%	
					Silicon, amorphous	7631-86-9	0.086	0.075%	20.00%	
					Phenol resin	(Trade secret)	0.043	0.038%	10.00%	
					Epoxy resin	(Trade secret)	0.043	0.038%	10.00%	
					Polypropylene copolymer (Dicing tape)	(Trade secret)	0.180	0.157%	41.90%	
					Acrylic resin	(Trade secret)	0.052	0.045%	12.00%	
					Polyethylene copolymer	(Trade secret)	0.018	0.015%	4.10%	
Substrate	Substrate	40.46	35.299	352992	Barium Sulfate	7727-43-7	2.913	2.542%	7.20%	
					Dipropylene glycolmonomethyl ether	34590-94-8	1.554	1.355%	3.84%	
					Talc containing noasbestiform fibers	14807-96-6	0.259	0.226%	0.64%	
					Epoxy resin	Trade seacret	1.424	1.243%	3.52%	
					Morpholine derivative	Trade seacret	0.259	0.226%	0.64%	
					Naphthalene	91-20-3	0.065	0.056%	0.16%	
					Cured thermosettingresin (includinginorganic filler)	Trade seacret	10.135	8.842%	25.05%	
					Continuous FilamentFiber Glass	Trade seacret	6.672	5.821%	16.49%	
					Bisphenol A Epoxy Resin	80-05-7	0.085	0.074%	0.21%	
					Copper	7440-50-8	16.540	14.430%	40.88%	
					Gold	7440-57-5	0.065	0.056%	0.16%	
Nickel	7440-02-0	0.490	0.427%	1.21%						
Molding Compound	Chip Protection	56.38	49.19	491,886	Silica (Fused)	60676-86-0	50.460	44.024%	89.50%	
					Epoxy resin	(Trade secret)	2.819	2.459%	5.00%	
					Phenol resin	(Trade secret)	2.819	2.459%	5.00%	
					Carbon Black	1333-86-4	0.282	0.246%	0.50%	
Solder Ball	Solder	8.70	7.59	75,903	Tin (Sn)	7440-31-5	8.396	7.325%	96.50%	
					Silver (Ag)	7440-22-4	0.261	0.228%	3.00%	
					Copper (Cu)	7440-50-8	0.044	0.038%	0.50%	